

**City University of Hong Kong
Course Syllabus**

**offered by Department of Materials Science and Engineering
with effect from Semester A in 2022/23**

Part I Course Overview

Course Title:	<u>Reliability Engineering in Electronics Industry</u>
Course Code:	<u>MSE6814</u>
Course Duration:	<u>One Semester</u>
Credit Units:	<u>3</u>
Level:	<u>P6</u>
Medium of Instruction:	<u>English</u>
Medium of Assessment:	<u>English</u>
Prerequisites: <i>(Course Code and Title)</i>	<u>Nil</u>
Precursors: <i>(Course Code and Title)</i>	<u>Nil</u>
Equivalent Courses: <i>(Course Code and Title)</i>	<u>Nil</u>
Exclusive Courses: <i>(Course Code and Title)</i>	<u>EE6614</u>

Part II Course Details

1. Abstract

The course aims to provide students with a fundamental understanding of the basic technology and applications to modern electronic packaging in consumer electronic products. The trend of packaging starting from wire-bonding, taping-automatic bonding, flip chip solder joints, micro solder-bumps, and Cu-to-Cu direct bonding as well as hybrid bonding will be covered.

The course is designed so that the students can learn the basic concepts in circuit design of 3D IC in electronic packaging technology. Especially, the materials integration in printed circuit board, multilayered interconnections in back-end-of-line, redistribution layer, Si interposer, through-Si-vias will be covered. Device reliability issues such as electromigration, thermomigration, and stress-migration will be explained clearly. Because Joule heating is the most serious cause of yield and reliability in modern consumer electronic products, the so-called low power device means low entropy or low waste heat production device. For device lifetime prediction, the mean-to-to failure equations will be derived based on entropy production in irreversible processes. How to measure the parameters in the equations will be discussed.

2. Course Intended Learning Outcomes (CILOs)

(CILOs state what the student is expected to be able to do at the end of the course according to a given standard of performance.)

No.	CILOs	Weighting* (if applicable)	Discovery-enriched curriculum related learning outcomes (please tick where appropriate)		
			A1	A2	A3
1.	Recognize the difference between chip technology and packaging technology.		✓		
2.	Can identify failure modes and its cause in modern electronic packaging technology.		✓	✓	
3.	Can perform failure analysis on electromigration, thermomigration and stress-migration.				✓
4.	Demonstrate independent ability to perform failure analysis as a failure engineer in electronic packaging industry.		✓	✓	
* If weighting is assigned to CILOs, they should add up to 100%.		100%			

A1: Attitude

Develop an attitude of discovery/innovation/creativity, as demonstrated by students possessing a strong sense of curiosity, asking questions actively, challenging assumptions or engaging in inquiry together with teachers.

A2: Ability

Develop the ability/skill needed to discover/innovate/create, as demonstrated by students possessing critical thinking skills to assess ideas, acquiring research skills, synthesizing knowledge across disciplines or applying academic knowledge to self-life problems.

A3: Accomplishments

Demonstrate accomplishment of discovery/innovation/creativity through producing /constructing creative works/new artefacts, effective solutions to real-life problems or new processes.

3. Teaching and Learning Activities (TLAs)

(TLAs designed to facilitate students' achievement of the CILOs.)

TLA	Brief Description	CILO No.						Hours/week (if applicable)
		1	2	3	4			
Lectures	The lectures will follow the chapters in the textbook	✓	✓	✓	✓			3hrs/wk (for 11 wks)
Presentation and Tests	Students will give presentations on topics related to the course. Tests will also be conducted.	✓	✓	✓	✓			3hrs/wk (for 2 wks)

4. Assessment Tasks/Activities (ATs)

(ATs are designed to assess how well the students achieve the CILOs.)

Assessment Tasks/Activities	CILO No.						Weighting*	Remarks
	1	2	3	4				
Continuous Assessment: <u>40 %</u>								
Tests (min.: 2)	✓	✓	✓	✓			30 %	
#Assignments (min.:3)	✓	✓	✓	✓			10 %	
Examination: <u>60 %</u> (duration: 2 hrs , if applicable)								
Examination	✓	✓	✓	✓			60 %	
							100%	

* The weightings should add up to 100%.

Remark:

To pass the course, students are required to achieve at least 30% in continuous assessment and 30% in the examination.

may include homework, tutorial exercise, project/mini-project, presentation

5. Assessment Rubrics

(Grading of student achievements is based on student performance in assessment tasks/activities with the following rubrics.)

Applicable to students admitted in Semester A 2022/23 and thereafter

Assessment Task	Criterion	Excellent (A+, A, A-)	Good (B+, B)	Marginal (B-, C+, C)	Failure (F)
1. Continuous Assessment	Achievements in CILOs	High	Moderate	Basic	Not even reaching marginal level
2. Examination	Achievements in CILOs	High	Moderate	Basic	Not even reaching marginal level

Applicable to students admitted before Semester A 2022/23

Assessment Task	Criterion	Excellent (A+, A, A-)	Good (B+, B, B-)	Fair (C+, C, C-)	Marginal (D)	Failure (F)
1. Continuous Assessment	Achievements in CILOs	High	Significant	Moderate	Basic	Not even reaching marginal level
2. Examination	Achievements in CILOs	High	Significant	Moderate	Basic	Not even reaching marginal level

6. Constructive Alignment with Programme Outcomes

PILO	How the course contribute to the specific PILO(s)
1-5	Awareness on the knowledge and analysis tools as a failure engineer in electronic packaging industry. Applications of learned knowledge and skills for practical cases in modern electronic packaging technology.

Part III Other Information (more details can be provided separately in the teaching plan)

1. Keyword Syllabus

- Cu-to-Cu and Other Bonding Technologies in Electronic Packaging
- Randomly Oriented and (111) Uni-directionally Oriented Nanotwin Copper
- Solid-Liquid Interfacial Diffusion Reactions (SLID) between Copper and Solder
- Solid State Reactions between Solder and Copper
- Essence of Integrated Circuits and Packaging Design
- Performance, Power, Thermal and Reliability
- 2.5D/3D System-in-Packaging Integration
- Irreversible Processes in Electronic Packaging Technology
- Electromigration
- Thermomigration
- Stress-Migration
- Failure Analysis
- Artificial Intelligence on Electronic Packaging Reliability

2. Reading List

2.1 Compulsory Readings

(Compulsory readings can include books, book chapters, or journal/magazine articles. There are also collections of e-books, e-journals available from the CityU Library.)

1.	Electronic Packaging Science and Technology by King-Ning Tu
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2.2 Additional Readings

(Additional references for students to learn to expand their knowledge about the subject.)

1.	Nil
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